

ACT8896

Rev 1, 06-Sep-13

Advanced PMU for Samsung S3C6410

FEATURES

- Optimized for Samsung S3C6410 Processor
- Three Step-Down DC/DC Converters
- Four Low-Dropout Linear Regulators
- I²C[™] Serial Interface
- Advanced Enable/Disable Sequencing Controller
- Minimal External Components
- Tiny 4×4mm TQFN44-32 Package
 - 0.75mm Package Height
 - Pb-Free and RoHS Compliant

GENERAL DESCRIPTION

The ACT8896 is a complete, cost effective, highlyefficient *ActivePMU*TM power management solution, optimized for the unique power, voltagesequencing, and control requirements of the Samsung S3C6410 processor.

This device features three step-down DC/DC converters and four low-noise, low-dropout linear regulators.

The three DC/DC converters utilize a highefficiency, fixed-frequency (2MHz), current-mode PWM control architecture that requires a minimum number of external components. Two DC/DCs are capable of supplying up to 900mA of output current, while the third supports up to 700mA. All four lowdropout linear regulators are high-performance, low-noise, regulators that supply up to 150mA, 150mA, 250mA, and 250mA, respectively.

The ACT8896 is available in a compact, Pb-Free and RoHS-compliant TQFN44-32 package.

TYPICAL APPLICATION DIAGRAM

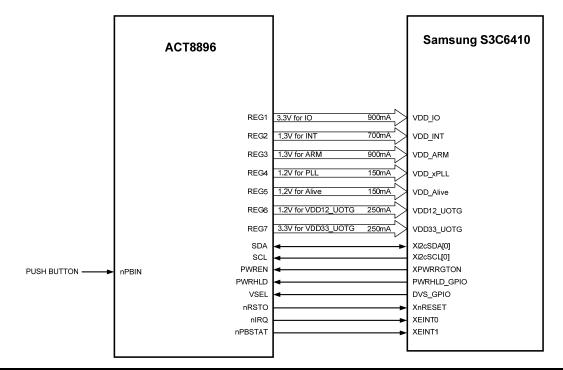






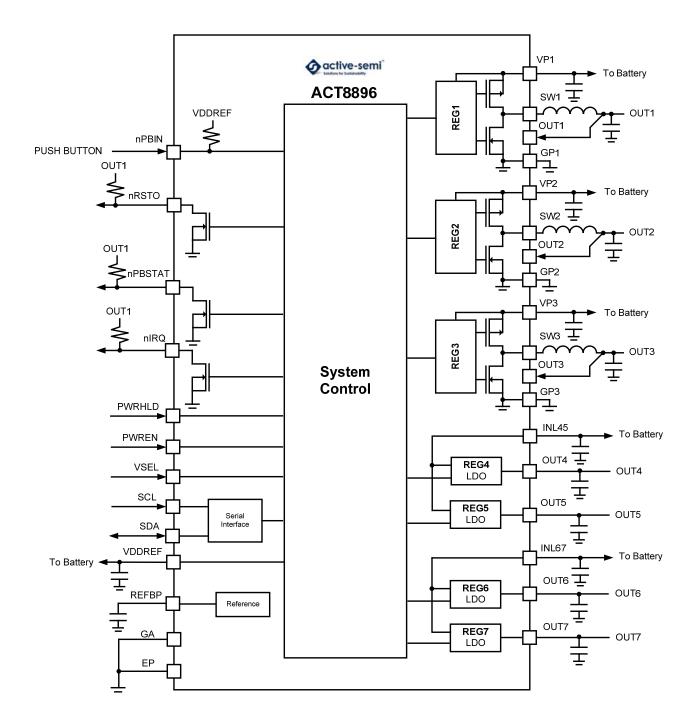
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FUNCTIONAL BLOCK DIAGRAM





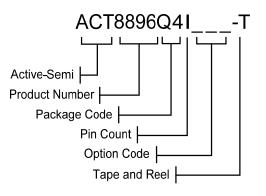
ORDERING INFORMATION^{0,2}

PART NUMBER	V _{out1} /V _{stby1} ®	V _{OUT2} /V _{STBY2}	V _{OUT3} /V _{STBY3}	V _{OUT4}	V _{out5}	V _{OUT6}	V _{OUT7}	PACKAGE	PINS	TEMPERATURE RANGE
ACT8896Q4I133-T	3.3V/3.3V	1.3V/1.3V	1.3V/1.3V	1.2V	1.2V	1.2V	3.3V	TQFN44-32	32	-40°C to +85°C

①: All Active-Semi components are RoHS Compliant and with Pb-free plating unless specified differently. The term Pb-free means semiconductor products that are in compliance with current RoHS (Restriction of Hazardous Substances) standards.

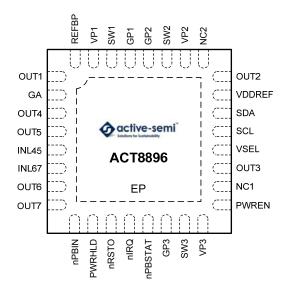
2: Standard product options are identified in this table. Contact factory for custom options, minimum order quantity is 12,000 units.

③: To select V_{STBYx} as a output regulation voltage of REGx, drive VSEL to a logic high. The V_{STBYx} can be set by software via I^2C interface, refer to appropriate sections of this datasheet for V_{STBYx} setting.



PIN CONFIGURATION

TOP VIEW



Thin - QFN (TQFN44-32)





PIN DESCRIPTIONS

PIN	NAME	DESCRIPTION
1	OUT1	Output Feedback Sense for REG1. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
2	GA	Analog Ground. Connect GA directly to a quiet ground node. Connect GA, GP1,GP2 and GP3 together at a single point as close to the IC as possible.
3	OUT4	Output Voltage for REG4. Capable of delivering up to 150mA of output current. Connect a 1.5μ F ceramic capacitor from OUT4 to GA. The output is discharged to GA with $1.5k\Omega$ resistor when disabled.
4	OUT5	Output Voltage for REG5. Capable of delivering up to 150mA of output current. Connect a 1.5μ F ceramic capacitor from OUT5 to GA. The output is discharged to GA with $1.5k\Omega$ resistor when disabled.
5	INL45	Power Input for REG4 and REG5. Bypass to GA with a high quality ceramic capacitor placed as close to the IC as possible.
6	INL67	Power Input for REG6 and REG7. Bypass to GA with a high quality ceramic capacitor placed as close to the IC as possible.
7	OUT6	Output Voltage for REG6. Capable of delivering up to 250mA of output current. Connect a 2.2μ F ceramic capacitor from OUT6 to GA. The output is discharged to GA with $1.5k\Omega$ resistor when disabled.
8	OUT7	Output Voltage for REG7. Capable of delivering up to 250mA of output current. Connect a 2.2μ F ceramic capacitor from OUT7 to GA. The output is discharged to GA with $1.5k\Omega$ resistor when disabled.
9	nPBIN	Master Enable Input. Drive nPBIN to GA through a $50k\Omega$ resistor to enable the IC, drive nPBIN directly to GA to assert a Hard-Reset condition. Refer to the <i>nPBIN Multi-Function Input</i> section for more information. nPBIN is internally pulled up to V _{VDDREF} through a $35k\Omega$ resistor.
10	PWRHLD	Power Hold Input. Refer to the Control Sequences section for more information.
11	nRSTO	Active Low Reset Output. See the <i>nRSTO Output</i> section for more information.
12	nIRQ	Open-Drain Interrupt Output. nIRQ asserts any time an unmasked fault condition exists or an interrupt occurs. See the <i>nIRQ Output</i> section for more information.
13	nPBSTAT	Active-Low Open-Drain Push-Button Status Output. nPBSTAT is asserted low whenever the nPBIN is pushed, and is high-Z otherwise. See the <i>nPBSTAT Output</i> section for more information.
14	GP3	Power Ground for REG3. Connect GA, GP1, GP2, and GP3 together at a single point as close to the IC as possible.
15	SW3	Switching Node Output for REG3. Connect this pin to the switching end of the inductor.
16	VP3	Power Input for REG3. Bypass to GP3 with a high quality ceramic capacitor placed as close to the IC as possible.
17	PWREN	Power Enable Input. Refer to the Control Sequences section for more information.
18	NC1	Not Connected. Not internally connected.
19	OUT3	Output Feedback Sense for REG3. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
20	VSEL	Step-Down DC/DCs Output Voltage Selection. Drive to logic low to select default output voltage. Drive to logic high to select secondary output voltage. See the <i>Output Voltage Programming</i> section for more information.
21	SCL	Clock Input for I ² C Serial Interface.
22	SDA	Data Input for I ² C Serial Interface. Data is read on the rising edge of SCL.





PIN DESCRIPTIONS CONT'D

PIN	NAME	DESCRIPTION
23	VDDREF	Power supply for the internal reference. Connect this pin directly to the system power supply. Bypass VDDREF to GA with a 1μ F capacitor placed as close to the IC as possible. Star connection with VP1, VP2 and VP3 preferred.
24	OUT2	Output Feedback Sense for REG2. Connect this pin directly to the output node to connect the internal feedback network to the output voltage.
25	NC2	Not Connected. Not internally connected.
26	VP2	Power Input for REG2 and System Control. Bypass to GP2 with a high quality ceramic capacitor placed as close to the IC as possible.
27	SW2	Switching Node Output for REG2. Connect this pin to the switching end of the inductor.
28	GP2	Power Ground for REG2. Connect GA, GP1,GP2 and GP3 together at a single point as close to the IC as possible.
29	GP1	Power Ground for REG1. Connect GA, GP1,GP2 and GP3 together at a single point as close to the IC as possible.
30	SW1	Switching Node Output for REG1. Connect this pin to the switching end of the inductor.
31	VP1	Power Input for REG1. Bypass to GP1 with a high quality ceramic capacitor placed as close to the IC as possible.
32	REFBP	Reference Bypass. Connect a 0.047 μ F ceramic capacitor from REFBP to GA. This pin is discharged to GA in shutdown.
EP	EP	Exposed Pad. Must be soldered to ground on PCB.





ABSOLUTE MAXIMUM RATINGS[®]

PARAMETER	VALUE	UNIT
VP1 to GP1, VP2 to GP2, VP3 to GP3	-0.3 to + 6	V
INL, VDDREF to GA	-0.3 to + 6	V
nPBIN, SCL, SDA, REFBP, PWRHLD, PWREN, VSEL to GA	-0.3 to (V _{VDDREF} + 0.3)	V
nRSTO, nIRQ, nPBSTAT to GA	-0.3 to + 6	V
SW1, OUT1 to GP1	-0.3 to (V _{VP1} + 0.3)	V
SW2, OUT2 to GP2	-0.3 to (V _{VP2} + 0.3)	V
SW3, OUT3 to GP3	-0.3 to (V _{VP3} + 0.3)	V
OUT4, OUT5, OUT6, OUT7 to GA	-0.3 to (V _{INL} + 0.3)	V
GP1, GP2, GP3 to GA	-0.3 to + 0.3	V
Junction to Ambient Thermal Resistance (θ_{JA})	27.5	°C/W
Operating Ambient Temperature	-40 to 85	°C
Maximum Junction Temperature	125	°C
Storage Temperature	-65 to 150	°C
Lead Temperature (Soldering, 10 sec)	300	°C

 \oplus : Do not exceed these limits to prevent damage to the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.





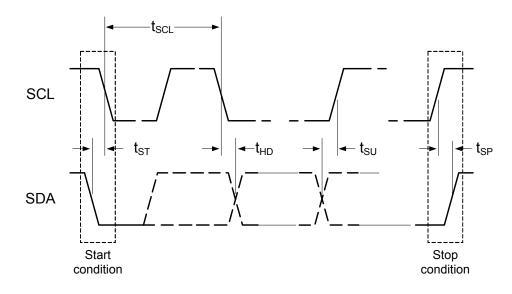
I²C INTERFACE ELECTRICAL CHARACTERISTICS

($V_{VP1} = V_{VP2} = V_{VP3} = 3.6V$, $T_A = 25^{\circ}C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SCL, SDA Input Low	V_{VDDREF} = 3.1V to 5.5V, T_A = -40°C to 85°C			0.35	V
SCL, SDA Input High	V_{VDDREF} = 3.1V to 5.5V, T_A = -40°C to 85°C	1.55			V
SDA Leakage Current				1	μA
SCL Leakage Current			1	2	μA
SDA Output Low	I _{OL} = 5mA			0.35	V
SCL Clock Period, t_{SCL}		1.5			μs
SDA Data Setup Time, t_{SU}		100			ns
SDA Data Hold Time, t_{HD}		300			ns
Start Setup Time, t_{ST}	For Start Condition	100			ns
Stop Setup Time, t _{SP}	For Stop Condition	100			ns

Figure 1:

I²C Compatible Serial Bus Timing







GLOBAL REGISTER MAP

						BITS	3			
OUTPUT	ADDRESS		D7	D6	D5	D4	D3	D2	D1	D0
SYS	0x00	NAME	TRST	nSYSMODE	nSYSLEVMSK	nSYSSTAT	SYSLEV[3]	SYSLEV[2]	SYSLEV[1]	SYSLEV[0]
515 UXUU	DEFAULT [®]	0	1	0	R	0	1	1	1	
eve	0,01	NAME	Reserved	Reserved	Reserved	Reserved	SCRATCH	SCRATCH	SCRATCH	SCRATCH
SYS	0x01	DEFAULT®	0	0	0	0	0	0	0	0
REG1	0x20	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
REGI	0,20	DEFAULT®	0	0	1	1	1	0	0	1
REG1	0x21	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
REGI	0,72,1	DEFAULT®	0	0	1	1	1	0	0	1
REG1	0x22	NAME	ON	PHASE	MODE	DELAY[2] ²	DELAY[1] ²	DELAY[0] [©]	nFLTMSK	OK
REGI	0x22	DEFAULT®	0	0	0	0	0	0	0	R
REG2	0.20	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
REGZ	0x30	DEFAULT [®]	0	0	0	1	1	0	1	0
	0.21	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
REG2	0x31	DEFAULT [®]	0	0	0	1	1	0	1	0
	0	NAME	ON	PHASE	MODE	DELAY[2] ²	DELAY[1] ²	DELAY[0] [©]	nFLTMSK	OK
REG2	0x32	DEFAULT [®]	0	0	0	0	0	0	0	R
DEOO	010	NAME	Reserved	Reserved	VSET1[5]	VSET1[4]	VSET1[3]	VSET1[2]	VSET1[1]	VSET1[0]
REG3	0x40	DEFAULT®	0	0	0	1	1	0	1	0
REG3 0x41	0.44	NAME	Reserved	Reserved	VSET2[5]	VSET2[4]	VSET2[3]	VSET2[2]	VSET2[1]	VSET2[0]
	0x41	DEFAULT®	0	0	0	1	1	0	1	0
	0.40	NAME	ON	PWRSTAT	MODE	DELAY[2] ²	DELAY[1] ²	DELAY[0] [©]	nFLTMSK	OK
REG3	0x42	DEFAULT [®]	0	0	0	0	0	0	0	R
	0.450	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
REG4	0x50	DEFAULT [®]	0	0	0	1	1	0	0	0
	0.451	NAME	ON	DIS	LOWIQ	DELAY[2] ²	DELAY[1] ²	DELAY[0] [©]	nFLTMSK	OK
REG4	0x51	DEFAULT®	0	1	0	0	0	0	0	R
DEOE	0.454	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
REG5	0x54	DEFAULT [®]	0	0	0	1	1	0	0	0
DEOE	0.4EE	NAME	ON	DIS	LOWIQ	DELAY[2] ²	DELAY[1] ²	DELAY[0] ²	nFLTMSK	OK
REG5	UX55	DEFAULT®	0	1	0	0	0	0	0	R
	0.400	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
REG5 0x55 REG6 0x60	DEFAULT®	0	0	0	1	1	0	0	0	
DEOC	0.01	NAME	ON	DIS	LOWIQ	DELAY[2] ²	DELAY[1] ²	DELAY[0] ²	nFLTMSK	OK
REG6	0x61	DEFAULT [®]	0	1	0	0	0	0	0	R
0507	004	NAME	Reserved	Reserved	VSET[5]	VSET[4]	VSET[3]	VSET[2]	VSET[1]	VSET[0]
REG7	0x64	DEFAULT [®]	0	0	1	1	1	0	0	1
0507	005	NAME	ON	DIS	LOWIQ	DELAY[2] ²	DELAY[1] ²	DELAY[0] ²	nFLTMSK	OK
REG7	0x65	DEFAULT [®]	0	1	0	0	0	0	0	R

1 Default values of ACT8896Q4I133-T.

2: Regulator turn-on delay bits. Automatically cleared to default values when the input power is removed or falls below the system UVLO.





REGISTER AND BIT DESCRIPTIONS

Table 1:

Global Register Map

OUTPUT	ADDRESS	BIT	NAME	ACCESS	DESCRIPTION
SYS	0x00	[7]	TRST	R/W	Reset Timer Setting. Defines the reset time-out threshold. Reset time-out is 65ms when value is 1, reset time-out is 260ms when value is 0. See <i>nRSTO Output</i> section for more information.
SYS	0x00	[6]	nSYSMODE	R/W	SYSLEV Mode Select. Defines the response to the SYSLEV voltage detector, 1: Generate an interrupt when V_{VDDREF} falls below the programmed SYSLEV threshold, 0: automatic shutdown when V_{VDDREF} falls below the programmed SYSLEV threshold.
SYS	0x00	[5]	nSYSLEVMSK	R/W	System Voltage Level Interrupt Mask. Disabled interrupt by default, set to 1 to enable this interrupt. See the <i>Programmable System Voltage Monitor</i> section for more information
SYS	0x00	[4]	nSYSSTAT	R	System Voltage Status. Value is 1 when V_{VDDREF} is lower than the SYSLEV voltage threshold, value is 0 when V_{VDDREF} is higher than the system voltage detection threshold.
SYS	0x00	[3:0]	SYSLEV	R/W	System Voltage Detect Threshold. Defines the SYSLEV voltage threshold. See the <i>Programmable System Voltage Monitor</i> section for more information.
SYS	0x01	[7:4]	-	R	Reserved.
SYS	0x01	[3:0]	SCRATCH	R/W	Scratchpad Bits. Non-functional bits, maybe be used by user to store system status information. Volatile bits, which are cleared upon system shutdown.
REG1	0x20	[7:6]	-	R	Reserved.
REG1	0x20	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG1	0x21	[7:6]	-	R	Reserved.
REG1	0x21	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG1	0x22	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG1	0x22	[6]	PHASE	R/W	Regulator Phase Control. Set bit to 1 for regulator to operate 180° out of phase with the oscillator, clear bit to 0 for regulator to operate in phase with the oscillator.
REG1	0x22	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transit to power-savings mode under light-load conditions.
REG1	0x22	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3</i> <i>Turn-on Delay</i> section for more information.
REG1	0x22	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault- interrupts, clear bit to 0 to disable fault-interrupts.
REG1	0x22	[0]	ОК	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG2	0x30	[7:6]	-	R	Reserved.
REG2	0x30	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG2	0x31	[7:6]	-	R	Reserved.





REGISTER AND BIT DESCRIPTIONS CONT'D

<u> </u>		B 15		100500	
OUTPUT	ADDRESS	BIT	NAME	ACCESS	DESCRIPTION
REG2	0x31	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG2	0x32	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG2	0x32	[6]	PHASE	R/W	Regulator Phase Control. Set bit to 1 for regulator to operate 180° out of phase with the oscillator, clear bit to 0 for regulator to operate in phase with the oscillator.
REG2	0x32	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transit to power-savings mode under light-load conditions.
REG2	0x32	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3 Turn-on Delay</i> section for more information.
REG2	0x32	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault- interrupts, clear bit to 0 to disable fault-interrupts.
REG2	0x32	[0]	ОК	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG3	0x40	[7:6]	-	R	Reserved.
REG3	0x40	[5:0]	VSET1	R/W	Primary Output Voltage Selection. Valid when VSEL is driven low. See the <i>Output Voltage Programming</i> section for more information.
REG3	0x41	[7:6]	-	R	Reserved.
REG3	0x41	[5:0]	VSET2	R/W	Secondary Output Voltage Selection. Valid when VSEL is driven high. See the <i>Output Voltage Programming</i> section for more information.
REG3	0x42	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG3	0x42	[6]	PWRSTAT	R/W	Configures regulator behavior with respect to the nPBIN input. Set bit to 0 to enable regulator when nPBIN is asserted.
REG3	0x42	[5]	MODE	R/W	Regulator Mode Select. Set bit to 1 for fixed-frequency PWM under all load conditions, clear bit to 0 to transition to power-savings mode under light-load conditions.
REG3	0x42	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG1, REG2, REG3 Turn-on Delay</i> section for more information.
REG3	0x42	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault- interrupts, clear bit to 0 to disable fault-interrupts.
REG3	0x42	[0]	ОК	R/W	Regulator Power-OK Status. Value is 1 when output voltage exceeds the power-OK threshold, value is 0 otherwise.
REG4	0x50	[7:6]	-	R	Reserved.
REG4	0x50	[5:0]	VSET	R/W	Output Voltage Selection. See the <i>Output Voltage</i> <i>Programming</i> section for more information.
REG4	0x51	[7]	ON	R/W	Regulator Enable Bit. Set bit to 1 to enable the regulator, clear bit to 0 to disable the regulator.
REG4	0x51	[6]	DIS	R/W	Output Discharge Control. When activated, discharges LDO output to GA through $1.5k\Omega$ when in shutdown. Set bit to 1 to enable output voltage discharge in shutdown, clear bit to 0 to disable this function.
REG4	0x51	[5]	LOWIQ	R/W	LDO Low-IQ Mode Control. Set bit to 1 for low-power operating mode, clear bit to 0 for normal mode.
REG4	0x51	[4:2]	DELAY	R/W	Regulator Turn-On Delay Control. See the <i>REG4, REG5, REG6, REG7 Turn-on Delay</i> section for more information.
REG4	0x51	[1]	nFLTMSK	R/W	Regulator Fault Mask Control. Set bit to 1 enable to fault- interrupts, clear bit to 0 to disable fault-interrupts.





REGISTER AND BIT DESCRIPTIONS CONT'D OUTPUT ADDRESS BIT NAME ACCESS DESCRIPTION Regulator Power-OK Status. Value is 1 when output voltage REG4 0x51 [0] OK R/W exceeds the power-OK threshold, value is 0 otherwise. REG5 0x54 [7:6] R Reserved. Output Voltage Selection. See the Output Voltage REG5 0x54 [5:0] VSET R/W Programming section for more information. Regulator Enable Bit. Set bit to 1 to enable the regulator, REG5 ON R/W 0x55 [7] clear bit to 0 to disable the regulator. Output Discharge Control, When activated, discharges LDO output to GA through $1.5k\Omega$ when in shutdown. Set bit to 1 to R/W REG5 DIS 0x55 [6] enable output voltage discharge in shutdown, clear bit to 0 to disable this function. LDO Low-IQ Mode Control. Set bit to 1 for low-power REG5 0x55 [5] LOWIQ R/W operating mode, clear bit to 0 for normal mode. Regulator Turn-On Delay Control. See the REG4, REG5, REG5 DELAY R/W 0x55 [4:2] REG6, REG7 Turn-on Delay section for more information. Regulator Fault Mask Control. Set bit to 1 enable to fault-REG5 0x55 [1] nFLTMSK R/W interrupts, clear bit to 0 to disable fault-interrupts. Regulator Power-OK Status. Value is 1 when output voltage REG5 0x55 [0] OK R/W exceeds the power-OK threshold, value is 0 otherwise. REG6 Reserved. 0x60 [7:6] R -Output Voltage Selection. See the Output Voltage VSET R/W REG6 0x60 [5:0] Programming section for more information. Regulator Enable Bit. Set bit to 1 to enable the regulator, REG6 0x61 ON R/W [7] clear bit to 0 to disable the regulator. Output Discharge Control. When activated, discharges LDO output to GA through $1.5k\Omega$ when in shutdown. Set bit to 1 to REG6 0x61 DIS R/W [6] enable output voltage discharge in shutdown, clear bit to 0 to disable this function. LDO Low-IQ Mode Control. Set bit to 1 for low-power REG6 0x61 [5] LOWIQ R/W operating mode, clear bit to 0 for normal mode. Regulator Turn-On Delay Control. See the REG4, REG5, REG6 0x61 [4:2] DELAY R/W REG6, REG7 Turn-on Delay section for more information. Regulator Fault Mask Control. Set bit to 1 enable to fault-RFG6 0x61 nFI TMSK R/W [1] interrupts, clear bit to 0 to disable fault-interrupts. Regulator Power-OK Status. Value is 1 when output voltage REG6 0x61 [0] OK R/W exceeds the power-OK threshold, value is 0 otherwise. REG7 [7:6] R Reserved. 0x64 _ Output Voltage Selection. See the Output Voltage REG7 0x64 VSET R/W [5:0] Programming section for more information. Regulator Enable Bit. Set bit to 1 to enable the regulator, RFG7 0x65 [7] ON R/W clear bit to 0 to disable the regulator. Output Discharge Control. When activated, discharges LDO output to GA through $1.5k\Omega$ when in shutdown. Set bit to 1 to REG7 R/W 0x65 [6] DIS enable output voltage discharge in shutdown, clear bit to 0 to disable this function. LDO Low-IQ Mode Control. Set bit to 1 for low-power REG7 0x65 LOWIQ R/W [5] operating mode, clear bit to 0 for normal mode. Regulator Turn-On Delay Control. See the REG4, REG5, REG7 0x65 [4:2] DELAY R/W REG6, REG7 Turn-on Delay section for more information. Regulator Fault Mask Control. Set bit to 1 enable to fault-REG7 0x65 nFLTMSK R/W [1] interrupts, clear bit to 0 to disable fault-interrupts. Regulator Power-OK Status. Value is 1 when output voltage REG7 0x65 OK R/W [0] exceeds the power-OK threshold, value is 0 otherwise.

Innovative Power[™] - 12 -Active-Semi Proprietary—For Authorized Recipients and Customers *ActivePMU*[™] is a trademark of Active-Semi. I²C[™] is a trademark of NXP.





SYSTEM CONTROL ELECTRICAL CHARACTERISTICS

 $(V_{VP1} = V_{VP2} = V_{VP3} = 3.6V, T_A = 25^{\circ}C$, unless otherwise specified.)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Input Voltage Range		2.7		5.5	V
UVLO Threshold Voltage	V _{VDDREF} Rising	2.2	2.45	2.65	V
UVLO Hysteresis	V _{VDDREF} Falling		200		mV
	REG1 and REG5 Enabled. REG2, REG3, REG4, REG6 and REG7 Disabled		185		
Supply Current	REG1, REG2, REG3, REG4 and REG5 Enabled. REG6 and REG7 Disabled		350		
	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 Enabled		420		
Shutdown Supply Current	All Regulators Disabled		1.5	3.0	μA
Oscillator Frequency		1.8	2	2.2	MHz
Logic High Input Voltage [®]		1.4			V
Logic Low Input Voltage				0.4	V
Leakage Current	$V_{nIRQ} = V_{nRSTO} = 4.2V$			1	μA
Low Level Output Voltage [©]	I _{SINK} = 5mA			0.35	V
nRSTO Delay			260 ³		ms
Thermal Shutdown Temperature	Temperature rising		160		°C
Thermal Shutdown Hysteresis			20		°C

10: PWRHLD, PWREN, VSEL are logic inputs.

2: nPBSTAT, nIRQ, nRSTO are open drain outputs.

③: Typical value shown. Actual value may vary from 227.9ms to 291.2ms.





STEP-DOWN DC/DC ELECTRICAL CHARACTERISTICS

 $(V_{VP1} = V_{VP2} = V_{VP3} = 3.6V, T_A = 25^{\circ}C$, unless otherwise specified.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Operating Voltage Range		2.7		5.5	V
UVLO Threshold	Input Voltage Rising	2.5	2.6	2.7	V
UVLO Hysteresis	Input Voltage Falling		100		mV
Quiescent Supply Current	Regulator Enabled		65	90	μA
Shutdown Current	V_{VP} = 5.5V, Regulator Disabled		0	1	μA
	V _{OUT} ≥ 1.2V, I _{OUT} = 10mA	-1%	$V_{\text{NOM}}^{\mathbb{O}}$	1%	
Output Voltage Accuracy	V _{OUT} < 1.2V, I _{OUT} = 10mA	-2%	$V_{NOM}^{\mathbb{O}}$	2%	- V
Line Regulation	$V_{VP} = Max(V_{NOM}^{\circ} + 1, 3.2V)$ to 5.5V		0.15		%/V
Load Regulation	I _{OUT} = 10mA to IMAX [©]		0.0017		%/mA
Power Good Threshold	V _{OUT} Rising		93		%V _{NOM}
Power Good Hysteresis	V _{OUT} Falling		2		$%V_{NOM}$
	$V_{OUT} \ge 20\%$ of V_{NOM}	1.8	2	2.2	MHz
Oscillator Frequency	V _{OUT} = 0V		500		kHz
Soft-Start Period			400		μs
Minimum On-Time			75		ns
REG1	·	•			
Maximum Output Current		0.9			А
Current Limit		1.2	1.4	1.7	А
PMOS On-Resistance	I _{SW1} = -100mA		0.18		Ω
NMOS On-Resistance	I _{SW1} = 100mA		0.16		Ω
SW1 Leakage Current	V _{VP1} = 5.5V, V _{SW1} = 0 or 5.5V		0	1	μA
REG2	·	•			
Maximum Output Current		0.7			А
Current Limit		0.9	1.1	1.3	А
PMOS On-Resistance	I _{SW2} = -100mA		0.21		Ω
NMOS On-Resistance	I _{SW2} = 100mA		0.16		Ω
SW2 Leakage Current	$V_{VP2} = 5.5V, V_{SW2} = 0 \text{ or } 5.5V$		0	1	μA
REG3	·	•			
Maximum Output Current		0.9			А
Current Limit		1.2	1.4	1.7	А
PMOS On-Resistance	I _{SW3} = -100mA		0.18		Ω
NMOS On-Resistance	I _{SW3} = 100mA		0.16		Ω
SW3 Leakage Current	V _{VP3} = 5.5V, V _{SW3} = 0 or 5.5V		0	1	μA

 $\oplus: V_{\text{NOM}}$ refers to the nominal output voltage level for V_{OUT} as defined by the Ordering Information section.

2: IMAX Maximum Output Current.





LOW-NOISE LDO ELECTRICAL CHARACTERISTICS

 $(V_{INL} = 3.6V, C_{OUT4} = C_{OUT5} = 1.5\mu F, C_{OUT6} = C_{OUT7} = 2.2\mu F, LOWIQ[] = [0], T_A = 25^{\circ}C, unless otherwise specified.)$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Operating Voltage Range		2.5		5.5	V
Quitout Voltage Acouracy	$V_{OUT} \ge 1.2V$, $T_A = 25^{\circ}C$, $I_{OUT} = 10mA$	-1%	V_{NOM}	2%	v
Output Voltage Accuracy	V_{OUT} < 1.2V, T_A = 25°C, I_{OUT} = 10mA	-2%	$V_{\text{NOM}}^{\text{O}}$	4%	v
Line Degulation	V _{INL} = Max (V _{OUT} + 0.5V, 3.6V) to 5.5V LOWIQ[] = [0]		0.05		mV/V
Line Regulation	V _{INL} = Max (V _{OUT} + 0.5V, 3.6V) to 5.5V LOWIQ[] = [1]		0.5		111070
Load Regulation	I _{OUT} = 1mA to IMAX [℗]		0.08		V/A
Dever Supply Dejection Datio	f = 1kHz, I _{OUT} = 20mA, V _{OUT} =1.2V		75		40
Power Supply Rejection Ratio	f = 10kHz, I _{OUT} = 20mA, V _{OUT} =1.2V		65		dB
	Regulator Enabled, LOWIQ[] = [0]		37	60	
Supply Current per Output	Regulator Enabled, LOWIQ[] = [1]		31	52	μA
	Regulator Disabled		0	1	1
Soft-Start Period	V _{OUT} = 2.9V		140		μs
Power Good Threshold	V _{OUT} Rising		89		%
Power Good Hysteresis	V _{OUT} Falling		3		%
Output Noise	I _{OUT} = 20mA, f = 10Hz to 100kHz, V _{OUT} = 1.2V		50		μV_{RMS}
Discharge Resistance	LDO Disabled, DIS[] = 1		1.5		kΩ
REG4					
Dropout Voltage [®]	I _{OUT} = 80mA, V _{OUT} > 3.1V		90	180	mV
Maximum Output Current		150			mA
Current Limit®	V_{OUT} = 95% of regulation voltage	200			mA
Stable C _{OUT4} Range		1.5		20	μF
REG5					
Dropout Voltage	I _{OUT} = 80mA, V _{OUT} > 3.1V		140	280	mV
Maximum Output Current		150			mA
Current Limit	V _{OUT} = 95% of regulation voltage	200			mA
Stable C _{OUT5} Range		1.5		20	μF
REG6					
Dropout Voltage	I _{OUT} = 120mA, V _{OUT} > 3.1V		90	180	mV
Maximum Output Current		250			mA
Current Limit	V_{OUT} = 95% of regulation voltage	300			mA
Stable Coute Range		2.2		20	μF
REG7	•				-
Dropout Voltage	I _{OUT} = 120mA, V _{OUT} > 3.1V		140	280	mV
Maximum Output Current		250			mA
Current Limit	V _{OUT} = 95% of regulation voltage	300			mA
Stable C _{OUT7} Range		2.2		20	μF

①: V_{NOM} refers to the nominal output voltage level for V_{OUT} as defined by the Ordering Information section.

2: IMAX Maximum Output Current.

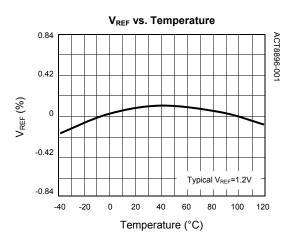
③: Dropout Voltage is defined as the differential voltage between input and output when the output voltage drops 100mV below the regulation voltage (for 3.1V output voltage or higher)

④: LDO current limit is defined as the output current at which the output voltage drops to 95% of the respective regulation voltage. Under heavy overload conditions the output current limit folds back by 30% (typ)

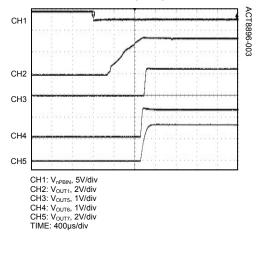


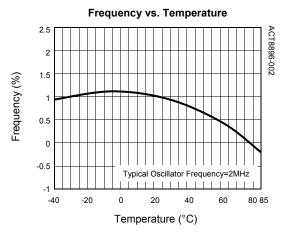


(V_{VP1} = V_{VP2} = V_{VP3} = 3.6V, T_A = 25°C, unless otherwise specified.)

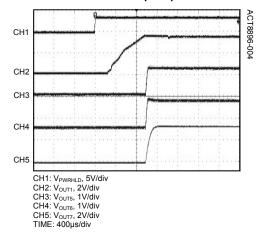


nPBIN Startup Sequence

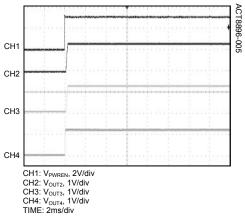




PWRHLD Startup Sequence

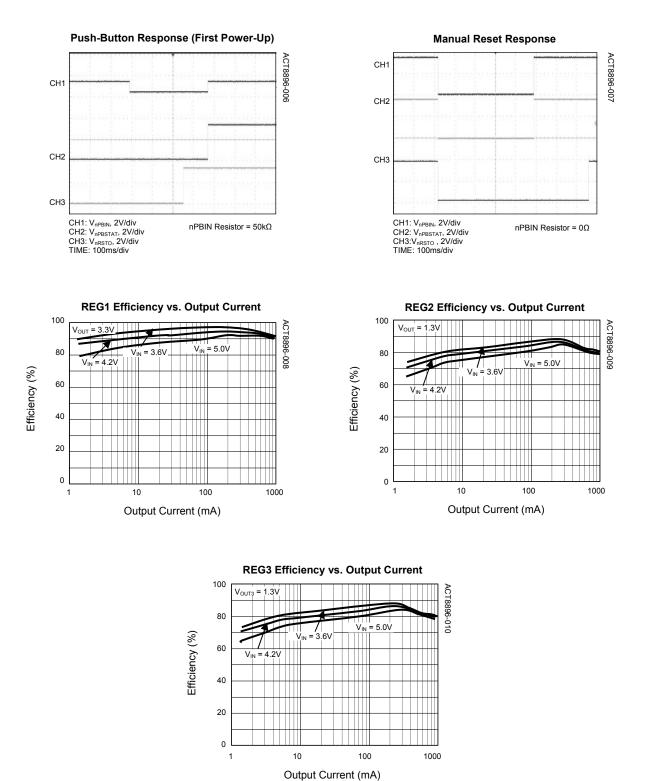






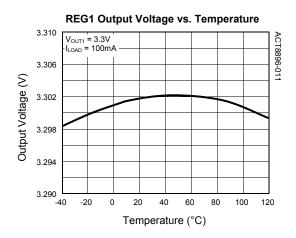


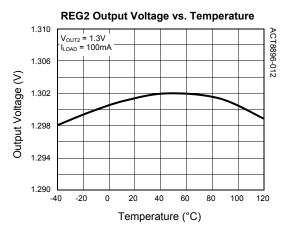






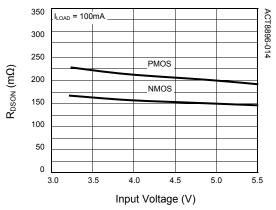




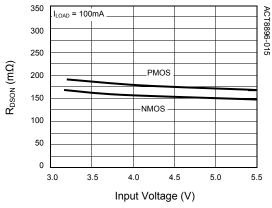


REG3 Output Voltage vs. Temperature 1.310 V_{OUT3} = 1.3V I_{LOAD} = 100mA ACT8896-013 1.306 Output Voltage (V) 1.302 1.298 1.294 1.290 -20 0 20 40 60 80 100 120 -40 Temperature (°C)

REG2 MOSFET Resistance

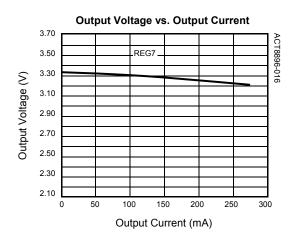




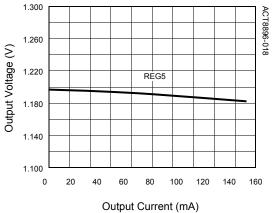


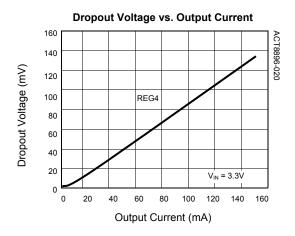


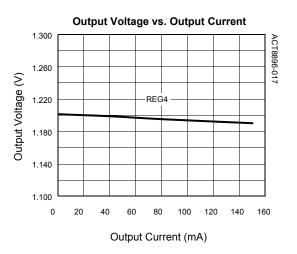




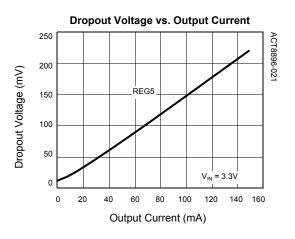






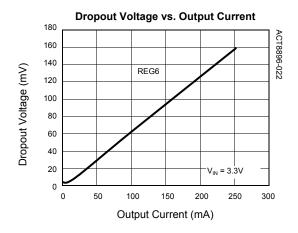


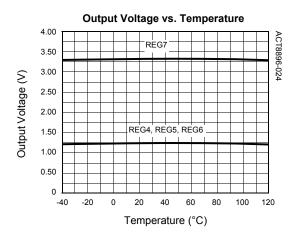
Output Voltage vs. Output Current 1.300 ACT8896-019 1.260 Output Voltage (V) 1.220 REG6 1.180 1.140 1.100 0 50 100 150 200 250 Output Current (mA)

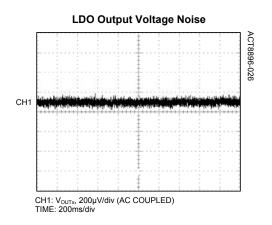


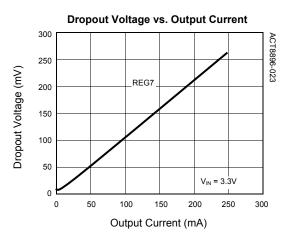




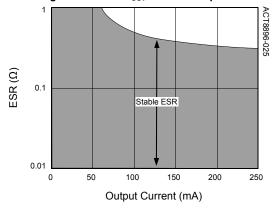








Region of Stable C_{OUT} ESR vs. Output Current





SYSTEM CONTROL INFORMATION

Interfacing with the Samsung S3C6410

The ACT8896 is optimized for use in applications using the S3C6410 processor, supporting both the power domains as well as the signal interface for these processors.

While the ACT8896 supports many possible configurations for powering these processors, one of the most common configurations is detailed in this datasheet. In general, this document refers to the ACT8896 pin names and functions. However, in cases where the description of interconnections between these devices benefits by doing so, both the ACT8896 pin names and the Samsung processor pin names are provided. When this is done, the S3C6410 pin names are located after the ACT8896 pin names, and are italicized and located inside parentheses. For example, PWREN (*XPWRRGTON*) refers to the logic signal applied to the ACT8896's PWREN input, identifying that it is driven from the S3C6410's XPWRRGTON output. Likewise, OUT1 (VDD_IO) refers to ACT8896's OUT1 pin, identifying that it is connected to the S3C6410's VDD_IO power domain.

Table 2:

ACT8896 and Samsung S3C6410 Power Domains

POWER DOMAIN	ACT8896 CHANNEL	TYPE	DEFAULT VOLTAGE	CURRENT CAPABILITY
VDD_IO	REG1	DC/DC	3.3V/3.3V	900mA
VDD_INT	REG2	DC/DC	1.3V/1.3V	700mA
VDD_ARM	REG3	DC/DC	1.3V/1.3V	900mA
VDD_xPLL	REG4	LDO	1.2V	150mA
VDD_Alive	REG5	LDO	1.2V	150mA
VDD12_UOTG	REG6	LDO	1.2V	250mA
VDD33_UOTG	REG7	LDO	3.3V	250mA

Table 3:

ACT8896 and Samsung S3C6410 Power Modes

POWER MODE	CONTROL STATE	POWER DOMAIN STATE	QUIESCENT CURRENT
ALL ON	PWRHLD is asserted, PWREN is asserted	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 are all on	420µA
NORMAL	PWRHLD is asserted, PWREN is asserted, REG6 and REG7 are disabled by I ² C	REG1, REG2, REG3, REG4 and REG5 are on. REG6 and REG7 are off	350µA
SLEEP	PWRHLD is asserted, PWREN is de-asserted, REG6 and REG7 are disabled by I ² C	REG1 and REG5 are on. REG2, REG3, REG4, REG6 and REG7 are off	185µA
ALL OFF	PWRHLD is de-asserted, PWREN is de- asserted	REG1, REG2, REG3, REG4, REG5, REG6 and REG7 are all off	<18µA



Table 4:

ACT8896 and Samsung S3C6410 Signal Interface

ACT8896	DIRECTION	SAMSUNG S3C6410
PWREN		XPWRRGTON
SCL	→	Xi2cSCL[0]
SDA	\longleftrightarrow	Xi2cSDA[0]
VSEL	→ · · · · · · · · · · · · · · · · · · ·	DVS_GPIO [®]
nRSTO	\longrightarrow	XnRESET
nIRQ	\longrightarrow	XEINT0 [©]
nPBSTAT	\longrightarrow	XEINT1 [®]
PWRHLD	<	Power hold GPIO®

①: Optional connection for DVS control.

②, ③: Typical connections shown, actual connections may vary.

(4): Optional connection for power hold control.

Table 5:

Control Pins

PIN NAME	OUTPUT		
nPBIN	REG1, REG5, REG6, REG7		
PWRHLD	REG1, REG5, REG6, REG7		
PWREN	REG2, REG3, REG4		

Control Signals

Enable Inputs

The ACT8896 features a variety of control inputs, which are used to enable and disable outputs depending upon the desired mode of operation. PWREN, PWRHLD are logic inputs, while nPBIN is a unique, multi-function input. Refer to Table 5 for a description of which channels are controlled by each input.

nPBIN Multi-Function Input

ACT8896 features the nPBIN multi-function pin, which combines system enable/disable control with a hardware reset function. Select either of the two pin functions by asserting this pin, either through a direct connection to GA, or through a 50k Ω resistor to GA, as shown in Figure 2.

Manual Reset Function

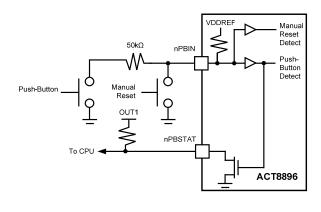
The second major function of the nPBIN input is to provide a manual-reset input for the processor. To manually-reset the processor, drive nPBIN directly to GA through a low impedance (less than 2.5k Ω). When this occurs, nRSTO immediately asserts low, then remains asserted low until the nPBIN input is de-asserted and the reset timeout period expires.

nPBSTAT Output

nPBSTAT is an open-drain output that reflects the state of the nPBIN input; nPBSTAT is asserted low whenever nPBIN is asserted, and is high-Z otherwise. This output is typically used as an interrupt signal to the processor, to initiate a software-programmable routine such as operating mode selection or to open a menu. Connect nPBSTAT to an appropriate supply voltage (typically OUT1) through a $10k\Omega$ or greater resistor.

Figure 2:

nPBIN Input





nRSTO Output

nRSTO is an open-drain output which asserts low upon startup or when manual reset is asserted via the nPBIN input. When asserted on startup, nRSTO remains low until reset timeout period expires after OUT1 reaches its power-OK threshold. When asserted due to manual-reset, nRSTO immediately asserts low, then remains asserted low until the nPBIN input is de-asserted and the reset timeout period expires.

Connect a $10k\Omega$ or greater pull-up resistor from nRSTO to an appropriate voltage supply (typically OUT1).

nIRQ Output

nIRQ is an open-drain output that asserts low any time an interrupt is generated. Connect a $10k\Omega$ or greater pull-up resistor from nIRQ to an appropriate voltage supply. nIRQ is typically used to drive the interrupt input of the system processor.

Many of the ACT8896's functions support interruptgeneration as a result of various conditions. These are typically masked by default, but may be unmasked via the I^2C interface. For more information about the available fault conditions, refer to the appropriate sections of this datasheet.

Note that under some conditions a false interrupt may be generated upon initial startup. For this reason, it is recommended that the interrupt service routine check and validate nSYSLEVMSK[] and nFLTMSK[] bits before processing an interrupt generated by these bits. These interrupts may be validated by nSYSSTAT[], OK[] bits.

Push-Button Control

The ACT8896 is designed to initiate a system enable sequence when the nPBIN multi-function input is asserted. Once this occurs, a power-on sequence commences, as described below. The power-on sequence must complete and the microprocessor must take control (by asserting PWREN or PWRHLD) before nPBIN is de-asserted. If the microprocessor is unable to complete its power-up routine successfully before the user lets the push-button go off, the ACT8896 automatically shuts the system down. This provides protection against accidental or momentary assertions of the push-button. If desired, longer "push-and-hold" times can be easily implemented by simply adding an additional time delay before asserting PWREN or PWRHLD.

Control Sequences

The ACT8896 features a variety of control

sequences that are optimized for supporting system enable and disable, as well as SLEEP mode of the Samsung S3C6410 processor.

Enabling/Disabling Sequence

A typical enable sequence initiates as a result of asserting nPBIN, and begins by enabling REG1. When REG1 reaches its power-OK threshold, REG5, REG6 and REG7 are enabled and nRSTO is asserted low, resetting the microprocessor. If REG1 is above its power-OK threshold when the reset timer expires, nRSTO is de-asserted, allowing the microprocessor to begin its boot sequence.

During the boot sequence, the microprocessor must assert PWRHLD, holding REG1, REG5, REG6 and REG7, and assert PWREN *(XPWRRGTON)*, enabling REG2, REG3 and REG4 to ensure that the system remains powered after nPBIN is released.

Once the power-up routine is completed, the system remains enabled after the push-button is released as long as either PWRHLD or PWREN are asserted high. If the processor does not assert PWRHLD or PWREN before the user releases the push-button, the boot-up sequence is terminated and all regulators are disabled. This provides protection against "false-enable", when the push-button is accidentally depressed, and also ensures that the system remains enabled only if the processor successfully completes the boot-up sequence.

As with the enable sequence, a typical disable sequence is initiated when the user presses the push-button, which interrupts the processor via the nPBSTAT output. The actual disable sequence is completely software-controlled, but typically involved initiating various "clean-up" processes then finally de-assert PWRHLD and PWREN, disabling all regulators and shutting the system down.

SLEEP Mode Sequence

The ACT8896 supports Samsung S3C6410 Processor's SLEEP mode operation. Once a successful power-up routine has been completed, SLEEP mode may be initiated through a variety of software-controlled mechanisms.

SLEEP mode is typically initiated when the user presses the push-button during normal operation. Pressing the push-button asserts the nPBIN input, which asserts the nPBSTAT output, which interrupts the processor. In response to this interrupt the processor should disable REG6 and REG7 via I²C first, then de-assert PWREN, disabling REG2, REG3, and REG4. PWRHLD should remain asserted during SLEEP mode so that





REG1 and REG5 remain enabled.

Waking from SLEEP mode is initiated when the user presses the push-button again, which enables REG6 and REG7, and asserts nPBSTAT.

Figure 3:

Enable/Disable Sequence

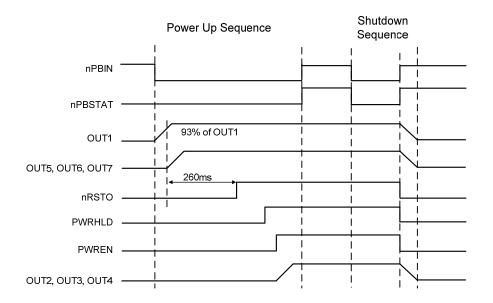
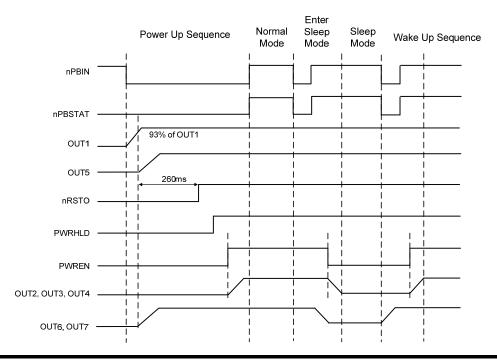


Figure 4: Sleep Mode Sequence



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FUNCTIONAL DESCRIPTION

I²C Interface

The ACT8896 features an I^2C interface that allows advanced programming capability to enhance overall system performance. To ensure compatibility with a wide range of system processors, the I^2C interface supports clock speeds of up to 400kHz ("Fast-Mode" operation) and uses standard I^2C commands. I^2C write-byte commands are used to program the ACT8896, and I^2C read-byte commands are used to read the ACT8896's internal registers. The ACT8896 always operates as a slave device, and is addressed using a 7-bit slave address followed by an eighth bit, which indicates whether the transaction is a readoperation or a write-operation, [1011011x].

SDA is a bi-directional data line and SCL is a clock input. The master device initiates a transaction by issuing a START condition, defined by SDA transitioning from high to low while SCL is high. Data is transferred in 8-bit packets, beginning with the MSB, and is clocked-in on the rising edge of SCL. Each packet of data is followed by an "Acknowledge" (ACK) bit, used to confirm that the data was transmitted successfully.

For more information regarding the I²C 2-wire serial interface, go to the NXP website: http://www.nxp.com.

Voltage Monitor and Interrupt

Programmable System Voltage Monitor

The ACT8896 features a programmable systemvoltage monitor, which monitors the voltage at VDDREF and compares it to a programmable threshold voltage. The programmable voltage threshold is programmed by SYSLEV[3:0], as shown in Table 6.

SYSLEV[] is set to 3.0V by default. There is a 200mV rising hysteresis on SYSLEV[] threshold such that V_{VDDREF} needs to be 3.2V(typ) or higher in order to power up the IC.

The nSYSSTAT[] bit reflects the output of an internal voltage comparator that monitors V_{VDDREF} relative to the SYSLEV[] voltage threshold, the value of nSYSTAT[] = 1 when V_{VDDREF} is lower than the SYSLEV[] voltage threshold, and nSYSTAT[] = 0 when V_{VDDREF} is higher than the SYSLEV[] voltage threshold. Note that the SYSLEV[] voltage threshold is defined for falling voltages, and that the comparator produces about 200mV of hysteresis at VDDREF. As a result, once V_{VDDREF} falls below the SYSLEV threshold, its voltage must increase by more than about 200mV to clear that condition.

After the IC is powered up, the ACT8896 responds in one of two ways when the voltage at VDDREF falls

1) If nSYSMODE[] = 1 (default case), when system voltage level interrupt is unmasked (nSYSLEVMSK[]=1) and V_{VDDREF} falls below the programmable threshold, the ACT8896 asserts nIRQ, providing a software "under-voltage alarm". The response to this interrupt is controlled by the CPU, but will typically initiate a controlled shutdown sequence either or alert the user that the battery is low. In this case the interrupt is cleared when V_{VDDREF} rises up again above the SYSLEV rising threshold and nSYSSTAT[] is read via l²C.

2) If nSYSMODE[] = 0, when V_{VDDREF} falls below the programmable threshold the ACT8896 shuts down, immediately disabling all regulators. This option is useful for implementing a programmable "under-voltage lockout" function that forces the system off when the battery voltage falls below the SYSLEV threshold voltage. Since this option does not support a controlled shutdown sequence, it is generally used as a "fail-safe" to shut the system down when the battery voltage is too low.

Table 6:

SYSLEV Falling Threshold

SYSLEV[3:0]	SYSLEV Falling Threshold (Hysteresis = 200mV)
0000	2.3
0001	2.4
0010	2.5
0011	2.6
0100	2.7
0101	2.8
0110	2.9
0111	3.0
1000	3.1
1001	3.2
1010	3.3
1011	3.4
1100	3.5
1101	3.6
1110	3.7
1111	3.8

Thermal Shutdown

The ACT8896 integrates thermal shutdown protection circuitry to prevent damage resulting from excessive thermal stress, as may be encountered under fault conditions. This circuitry disables all regulators if the ACT8896 die temperature exceeds 160°C, and prevents the regulators from being enabled until the IC temperature drops by 20°C (typ).



STEP-DOWN DC/DC REGULATORS

General Description

The ACT8896 features three synchronous, fixedfrequency, current-mode PWM step down converters that achieve peak efficiencies of up to 97%. REG1 and REG3 are capable of supplying up to 900mA of output current, while REG2 supports up to 700mA. These regulators operate with a fixed frequency of 2MHz, minimizing noise in sensitive applications and allowing the use of small external components.

100% Duty Cycle Operation

Each regulator is capable of operating at up to 100% duty cycle. During 100% duty-cycle operation, the high-side power MOSFET is held on continuously, providing a direct connection from the input to the output (through the inductor), ensuring the lowest possible dropout voltage in battery powered applications.

Synchronous Rectification

REG1, REG2, and REG3 each feature integrated nchannel synchronous rectifiers, maximizing efficiency and minimizing the total solution size and cost by eliminating the need for external rectifiers.

Soft-Start

When enabled, each output voltages tracks an internal 400µs soft-start ramp, minimizing input current during startup and allowing each regulator to power up in a smooth, monotonic manner that is independent of output load conditions.

Compensation

Each buck regulator utilizes current-mode control and a proprietary internal compensation scheme to simultaneously simplify external component selection and optimize transient performance over its full operating range. No compensation design is required; simply follow a few simple guidelines described below when choosing external components.

Input Capacitor Selection

The input capacitor reduces peak currents and noise induced upon the voltage source. A 4.7μ F ceramic capacitor is recommended for each regulator in most applications.

Output Capacitor Selection

For most applications, 22μ F ceramic output capacitors are recommended for REG1 and REG3, while 15μ F ceramic output capacitor is recommended for REG2.

Despite the advantages of ceramic capacitors, care must be taken during the design process to ensure stable operation over the full operating voltage and temperature range. Ceramic capacitors are available in a variety of dielectrics, each of which exhibits different characteristics that can greatly affect performance over their temperature and voltage ranges.

Two of the most common dielectrics are Y5V and X5R. Whereas Y5V dielectrics are inexpensive and can provide high capacitance in small packages, their capacitance varies greatly over their voltage and temperature ranges and are not recommended for DC/DC applications. X5R and X7R dielectrics are more suitable for output capacitor applications, as their characteristics are more stable over their operating ranges, and are highly recommended.

Inductor Selection

REG1, REG2, and REG3 utilize current-mode control and a proprietary internal compensation scheme to simultaneously simplify external component selection and optimize transient performance over their full operating range. These devices were optimized for operation with 2.2 μ H inductors, although inductors in the 1.5 μ H to 3.3 μ H range can be used. Choose an inductor with a low DC-resistance, and avoid inductor saturation by choosing inductors with DC ratings that exceed the maximum output current by at least 30%.

Configuration Options

Output Voltage Programming

By default, each regulator powers up and regulates to its default output voltage. Output voltage is selectable by setting VSEL pin that when VSEL is low, output voltage is programmed by VSET1[] bits, and when VSEL is high, output voltage is programmed by VSET2[] bits. However, once the system is enabled, each regulator's output voltage may be independently programmed to a different value, typically in order to power minimize the consumption of the microprocessor during some operating modes. Program the output voltages via the I²C serial interface by writing to the regulator's VSET1[] register if VSEL is low or VSET2[] register if VSEL is high as shown in Table 7.

Enable / Disable Control

During normal operation, each buck may be enabled or disabled via the I^2C interface by writing to that regulator's ON[] bit. The regulator accept rising or falling edge of ON[] bit as on/off signal. To enable the regulator, clear ON[] to 0 first then set to 1. To



disable the regulator, set ON[] to 1 first then clear it to 0.

REG1, REG2, REG3 Turn-on Delay

Each of REG1, REG2 and REG3 features a programmable Turn-on Delay which help ensure a reliable qualification. This delay is programmed by DELAY[2:0], as shown in Table 7.

Table 7:

REGx/DELAY[] Turn-On Delay

DELAY[2]	DELAY[1]	DELAY[0]	TURN-ON DELAY
0	0	0	0 ms
0	0	1	2 ms
0	1	0	4 ms
0	1	1	8 ms
1	0	0	16 ms
1	0	1	32 ms
1	1	0	64 ms
1	1	1	128 ms

Operating Mode

By default, REG1, REG2, and REG3 each operate in fixed-frequency PWM mode at medium to heavy loads, while automatically transitioning to a proprietary power-saving mode at light loads in order to maximize standby battery life. In applications where low noise is critical, force fixed-frequency PWM operation across the entire load current range, at the expense of light-load efficiency, by setting the MODE[] bit to 1.

OK[] and Output Fault Interrupt

Each DC/DC features a power-OK status bit that can be read by the system microprocessor via the l^2C

Table 8:

REGx/VSET[2:0]	REGx/VSET[5:3]							
	000	001	010	011	100	101	110	111
000	0.600	0.800	1.000	1.200	1.600	2.000	2.400	3.200
001	0.625	0.825	1.025	1.250	1.650	2.050	2.500	3.300
010	0.650	0.850	1.050	1.300	1.700	2.100	2.600	3.400
011	0.675	0.875	1.075	1.350	1.750	2.150	2.700	3.500
100	0.700	0.900	1.100	1.400	1.800	2.200	2.800	3.600
101	0.725	0.925	1.125	1.450	1.850	2.250	2.900	3.700
110	0.750	0.950	1.150	1.500	1.900	2.300	3.000	3.800
111	0.775	0.975	1.175	1.550	1.950	2.350	3.100	3.900

REGx/VSET[] Output Voltage Setting

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interface. If an output voltage is lower than the power-OK threshold, typically 7% below the programmed regulation voltage, that regulator's OK[] bit will be 0.

If a DC/DC's nFLTMSK[] bit is set to 1, the ACT8896 will interrupt the processor if that DC/DC's output voltage falls below the power-OK threshold. In this case, nIRQ will assert low and remain asserted until the OK[] bit has been read via I²C.

PCB Layout Considerations

High switching frequencies and large peak currents make PC board layout an important part of step-down DC/DC converter design. A good design minimizes excessive EMI on the feedback paths and voltage gradients in the ground plane, both of which can result in instability or regulation errors.

Step-down DC/DCs exhibit discontinuous input current, so the input capacitors should be placed as close as possible to the IC, and avoiding the use of via if possible. The inductor, input filter capacitor, and output filter capacitor should be connected as close together as possible, with short, direct, and wide traces. The ground nodes for each regulator's power loop should be connected at a single point in a starground configuration, and this point should be connected to the backside around plane with multiple via. The output node for each regulator should be connected to its corresponding OUTx pin through the shortest possible route, while keeping sufficient distance from switching nodes to prevent noise injection. Finally, the exposed pad should be directly connected to the backside ground plane using multiple via to achieve low electrical and thermal resistance.





LOW-NOISE, LOW-DROPOUT LINEAR REGULATORS

General Description

REG4, REG5, REG6, and REG7 are low-noise, low-dropout linear regulators (LDOs) that supply up to 150mA, 150mA, 250mA, and 250mA, respectively. Each LDO has been optimized to achieve low noise and high-PSRR, achieving more than 65dB PSRR at frequencies up to 10kHz.

Output Current Limit

Each LDO contains current-limit circuitry featuring a current-limit fold-back function. During normal and moderate overload conditions, the regulators can support more than their rated output currents. During extreme overload conditions, however, the current limit is reduced by approximately 30%, reducing power dissipation within the IC.

Compensation

The LDOs are internally compensated and require very little design effort, simply select input and output capacitors according to the guidelines below.

Input Capacitor Selection

Each LDO requires a small ceramic input capacitor to supply current to support fast transients at the input of the LDO. Bypassing each INL pin to GA with 1μ F. High quality ceramic capacitors such as X7R and X5R dielectric types are strongly recommended.

Output Capacitor Selection

Each LDO requires a small ceramic output capacitor for stability. Capacitance value is 1.5μ F for REG4 and REG5, 2.2μ F for REG6 and REG7. For best performance, each output capacitor should be connected directly between the output and GA pins, as close to the output as possible, and with a short, direct connection. High quality ceramic capacitors such as X7R and X5R dielectric types are strongly recommended.

Configuration Options

Output Voltage Programming

By default, each LDO powers up and regulates to its default output voltage. Once the system is enabled, each output voltage may be independently programmed to a different value by writing to the regulator's VSET[] register via the I²C serial interface as shown in Table 8.

Enable / Disable Control

During normal operation, each LDO may be enabled or disabled via the I²C interface by writing

to that LDO's ON[] bit. The regulator accept rising or falling edge of ON[] bit as on/off signal. To enable the regulator, clear ON[] to 0 first then set to 1. To disable the regulator, set ON[] to 1 first then clear it to 0.

REG4, REG5, REG6, REG7 Turn-on Delay

Each of REG4, REG5, REG6 and REG7 features a programmable Turn-on Delay which help ensure a reliable qualification. This delay is programmed by DELAY[2:0], as shown in Table 7.

Output Discharge

Each of the ACT8896's LDOs features an optional output discharge function, which discharges the output to ground through a $1.5k\Omega$ resistance when the LDO is disabled. This feature may be enabled or disabled by setting DIS[] via; set DIS[] to 1 to enable this function, clear DIS[] to 0 to disable it.

Low-Power Mode

Each of ACT8896's LDOs features a LOWIQ[] bit which, when set to 1, reduces the LDO's quiescent current by about 16%, saving power and extending battery lifetime.

OK[] and Output Fault Interrupt

Each LDO features a power-OK status bit that can be read by the system microprocessor via the interface. If an output voltage is lower than the power-OK threshold, typically 11% below the programmed regulation voltage, the value of that regulator's OK[] bit will be 0.

If a LDO's nFLTMSK[] bit is set to 1, the ACT8896 will interrupt the processor if that LDO's output voltage falls below the power-OK threshold. In this case, nIRQ will assert low and remain asserted until the OK[] bit has been read via I^2C .

PCB Layout Considerations

PCB Layout Considerations The ACT8896's LDOs provide good DC, AC, and noise performance over a wide range of operating conditions, and are relatively insensitive to layout considerations. When designing a PCB, however, careful layout is necessary to prevent other circuitry from degrading LDO performance.

A good design places input and output capacitors as close to the LDO inputs and output as possible, and utilizes a star-ground configuration for all regulators to prevent noise-coupling through ground. Output traces should be routed to avoid close proximity to noisy nodes, particularly the SW





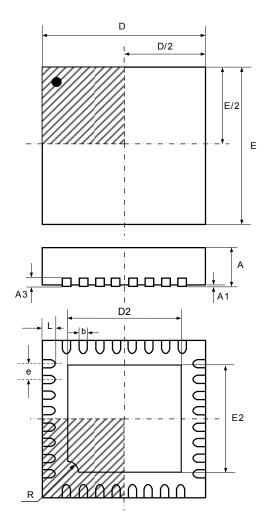
nodes of the DC/DCs.

REFBP is a filtered reference noise, and internally has a direct connection to the linear regulator controller. Any noise injected onto REFBP will directly affect the outputs of the linear regulators, and therefore special care should be taken to ensure that no noise is injected to the outputs via REFBP. As with the LDO output capacitors, the REFBP bypass capacitor should be placed as close to the IC as possible, with short, direct connections to the star-ground. Avoid the use of via whenever possible. Noisy nodes, such as from the DC/DCs, should be routed as far away from REFBP as possible.





TQFN44-32 PACKAGE OUTLINE AND DIMENSIONS



SYMBOL		SION IN ETERS	DIMENSION IN INCHES		
	MIN MAX		MIN	MAX	
А	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A3	0.2	200	0.008		
b	0.150	0.250	0.006	0.010	
D	4.000) TYP	0.158 TYP		
E	4.000 TYP		0.158 TYP		
D2	2.550	2.800	0.100	0.110	
E2	2.550	2.800	0.100	0.110	
е	0.400 TYP		0.016 TYP		
L	0.250	0.450	0.010	0.018	
R	0.250		0.010		

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